

Cure Schedule – Copper-Based Conductive

Mold Size Diameter	Number of Scoops	Powder Amount (g)	Cure Time (min)	Heat Temp (°C/°F)	Cool Time (min)	Mold Pressure (psi)
1" & 25 mm	1	24	1	180/356	4	4400
1.25" & 30 mm	1.5	37	1		4	4000
1.5" & 40 mm	2	49	1		4	3800
2" & 50 mm	3.5	85	1		6	3500

Notes:

- For single mounts. If duplexing, may need to add 1 minute to cure time.
- Powder amount may vary depending on the size of each sample.
- All samples must be ultrasonically cleaned and dried to remove any debris and/or grease.
- Mold Release agent must be applied every time before a mounting cycle (200-10006 PTFE Spray is recommended).
- Cure cycle times and temperatures may vary for non-Allied presses.